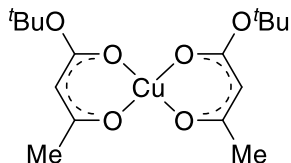


Catalog # 29-7110 Bis(t-butylacetoacetato)copper(II), 99%



Thermal Behavior:

- Melting point: 110°C [1], 133°C [5]
- Decomposition: ~330°C [5]
- TGA diagram and data is available in [1, 5]

Technical Notes:

1. CVD precursor for thin copper film deposition

Target Deposit	Deposition Technique	Delivery Temperature	Pressure	Co-reactants	Deposition Temperature	Ref.
Cu	CVD	90-135°C	50 Torr	Ar/H ₂	200-350°C	2
	CVD	120°C	10 Torr	Ar/H ₂	200-450°C	3
	CVD/Joule heat	150°C	1.25 Torr	Ar/H ₂	225°C	4
CuO _x	CVD	100-130°C	5 Torr	O ₂	400°C	5

References:

1. [J. Therm. Anal. Calorim. 1999, 55, 259](#)
2. [J. Mater. Sci. Lett. 1996, 15, 573](#)
3. [Surf. Coat. Tech. 2002, 150, 205](#)
4. [ACS Appl. Nano Mater. 2019, 2, 118](#)
5. [Inorg. Chem. 2021, 60, 17141](#)